STM32MiniDevBoardV1

Top View

PB8 PB9 PB7 PB6 PB5 PB4 PB3 PA15 PA14 PA13 PA10 PA9 PA8 PB15 PB14 3V3 GND VCC

BOOT_0 NRST_PIN

USB

AMS

PA0 PA1 PA2 PA3 PA4 PA5 PA6 PA7 PB0 PB1 PB2 PB10 PB11 PB12 PB13 3V3 GND VCC
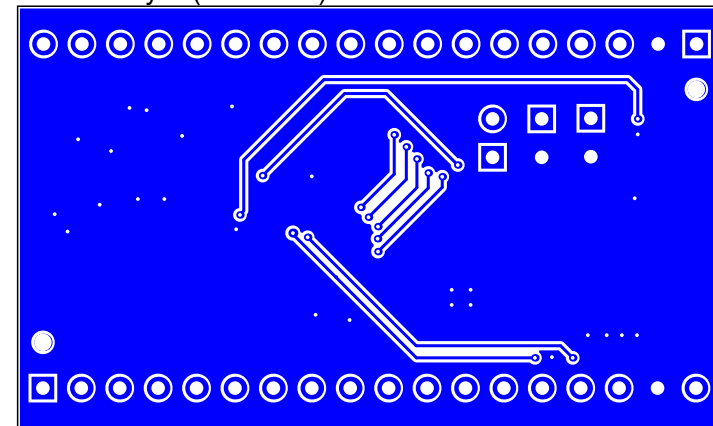
Bottom View

STM32MiniDevBoardV1
Designed By
Patsaoglou P.
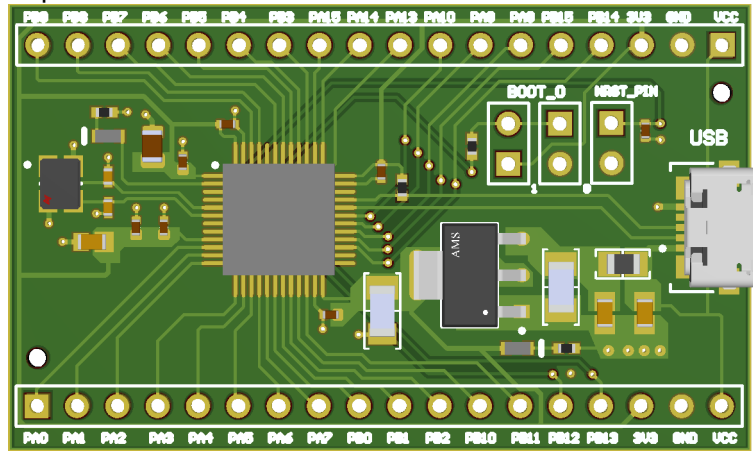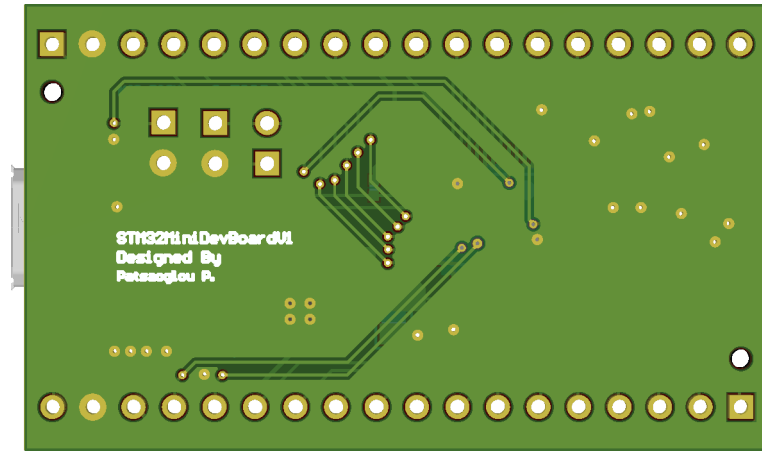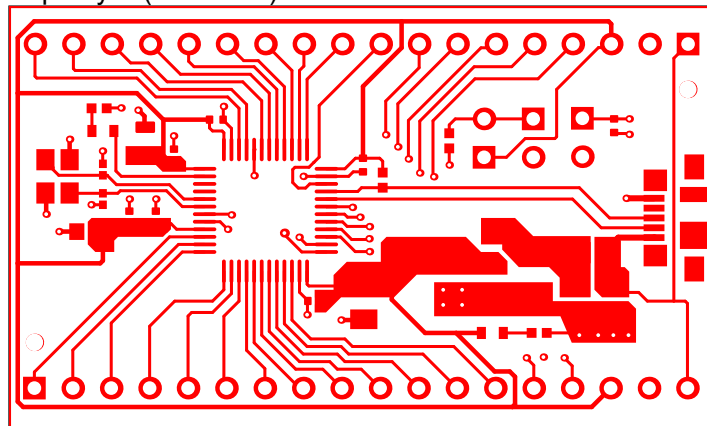
Top Layer (Scale 2:1)

Bottom Layer (Scale 2:1)
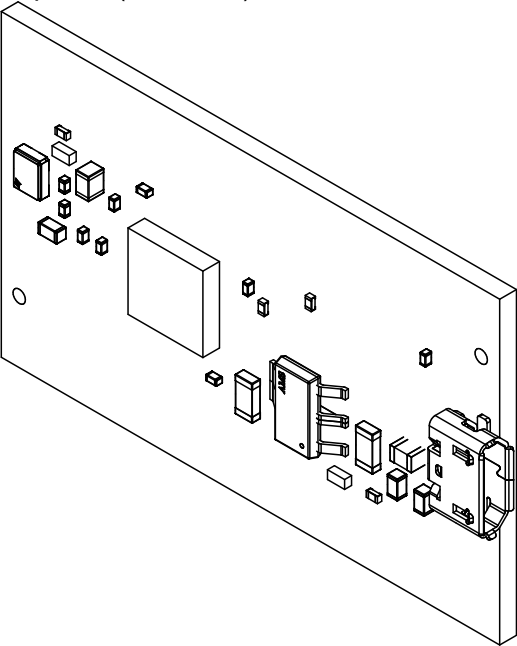
Top side (Scale 2:1)

Top side (Scale 1:1)
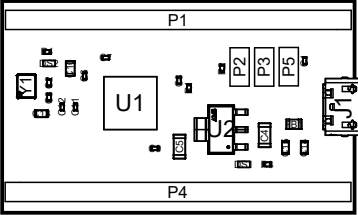
Top side (Scale 1:1)

Layer Stack

Total thickness: 1.66mm
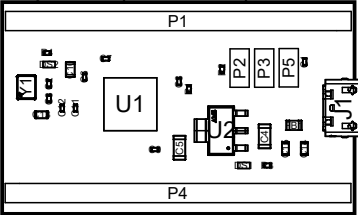
Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.03mm	SM-001	Solder Mask	GTS
PbSn	Top Surface Finish	0.02mm		Surface Finish	
CF-004	**Top Layer**	**0.04mm**		**Signal**	**GTL**
Core		*1.50mm*	*Core-043*	*Dielectric*	
CF-004	**Bottom Layer**	**0.04mm**		**Signal**	**GBL**
PbSn	Bottom Surface Finish	0.02mm		Surface Finish	
Surface Material	Bottom Solder	0.03mm	SM-001	Solder Mask	GBS
	Bottom Overlay			Legend	GBO